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SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



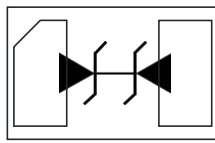
PLED

Product data sheet

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DFN1610-2L



Marking D5N

Feature

- 1500W Peak pulse power per line ($t_P = 8/20\mu s$)
- DFN1610-2L package
- Response time is typically $< 1\text{ ns}$
- Protect one I/O or power line
- Low clamping Voltage
- RoHS compliant
- Transient protection for data lines to
IEC 61000-4-2(ESD) $\pm 30\text{KV}$ (air), $\pm 30\text{KV}$ (contact);
IEC 61000-4-4 (EFT) 40A (5/50ns)

Applications

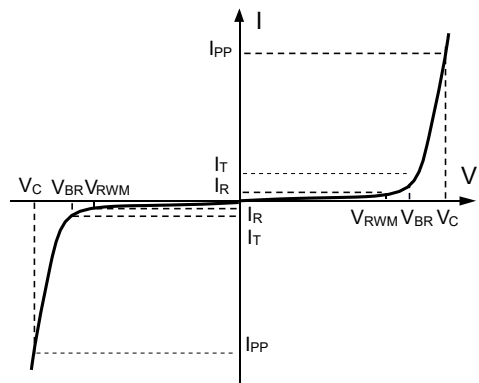
- Cell phone handsets and accessories
- Personal digital assistants (PDA's)
- Notebooks, desktops, and servers
- Portable instrumentation
- Cordless phones
- Digital cameras
- Peripherals
- MP3 players

Mechanical Characteristics

- Lead finish:100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:260°C
- Pure tin plating: 7 ~ 17 μm
- Pin flatness : $\leq 3\text{mil}$
- Device meets MSL 3 requirements

Electronics Parameter

Symbol	Parameter
V_{RWM}	Peak Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
P_{PP}	Peak Pulse Power
C_J	Junction Capacitance



Electrical characteristics per line@25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Peak Reverse Working Voltage	V_{RWM}				5.0	V
Breakdown Voltage	V_{BR}	$I_t = 1mA$	5.5		7.5	V
Reverse Leakage Current	I_R	$V_{RWM} = 5V T=25^{\circ}C$			1.0	μA
Clamping Voltage	V_C	$I_{PP}=20A t_P = 8/20\mu s$		8.0	10	V
Clamping Voltage	V_C	$I_{PP}=50A t_P = 8/20\mu s$		9.0	11	V
Clamping Voltage	V_C	$I_{PP}=100A t_P = 8/20\mu s$		10	12	V
Clamping Voltage	V_C	$I_{PP}=140A t_P = 8/20\mu s$		11	13	V
Junction Capacitance	C_j	$V_R=0V f = 1MHz$		400	450	pF

Note

- 1) VRWM is the maximum reverse working voltage, or reverse stand-off voltage. ESD can protect signal line properly within its rated voltage. If the signal line's voltage is over VRWM, ESD will change to other state.

Absolute maximum rating@25°C

Rating	Symbol	Value	Units
Peak Pulse Power ($t_P = 8/20\mu s$)	P_{PP}	1500	W
Peak Pulse Current ($t_P = 8/20\mu s$)	I_{PP}	140	A
Lead Soldering Temperature	T_L	260 (10 sec)	$^{\circ}C$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^{\circ}C$

Typical Characteristics

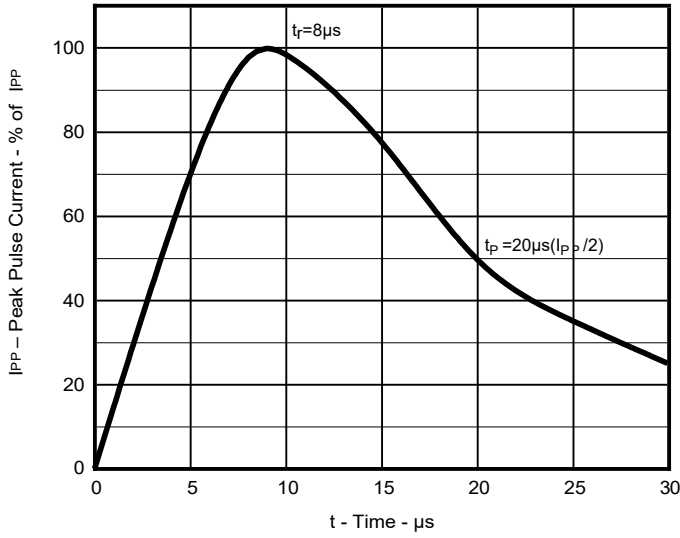


Fig 1. Pulse Waveform(8/20µs)

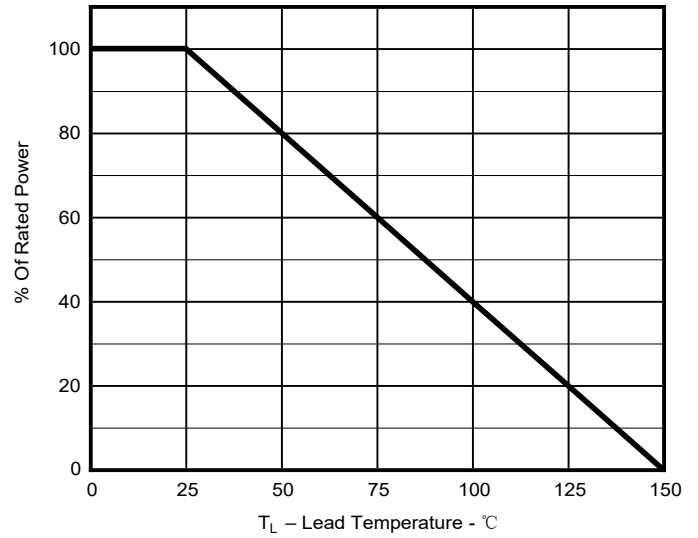


Fig 2. Power Derating Curve

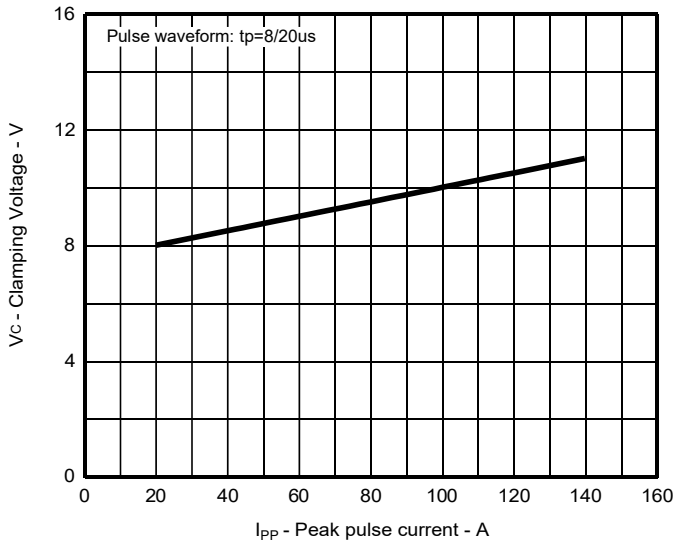


Fig 3. Clamping voltage vs. Peak pulse current

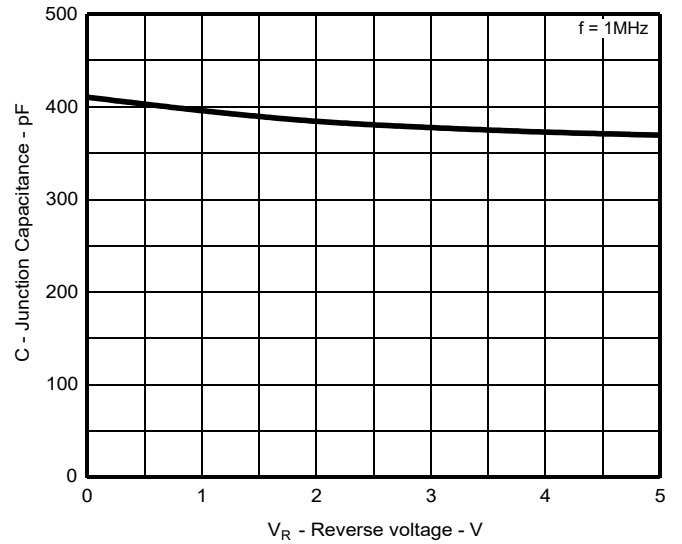


Fig 4. Capacitance vs. Reverse voltage

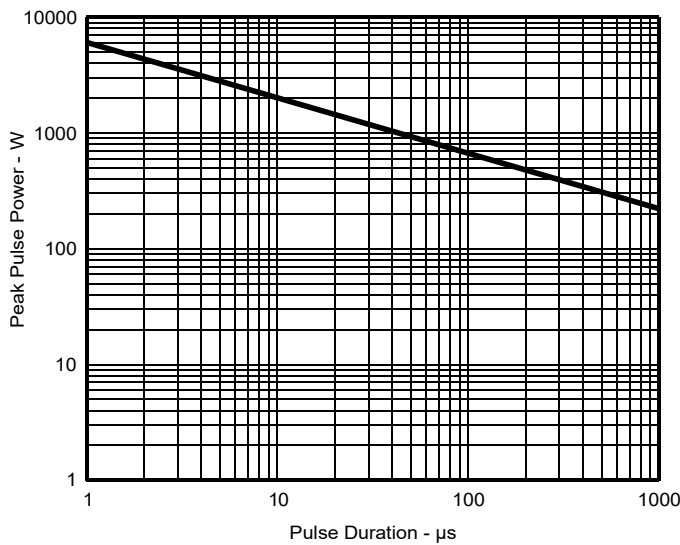
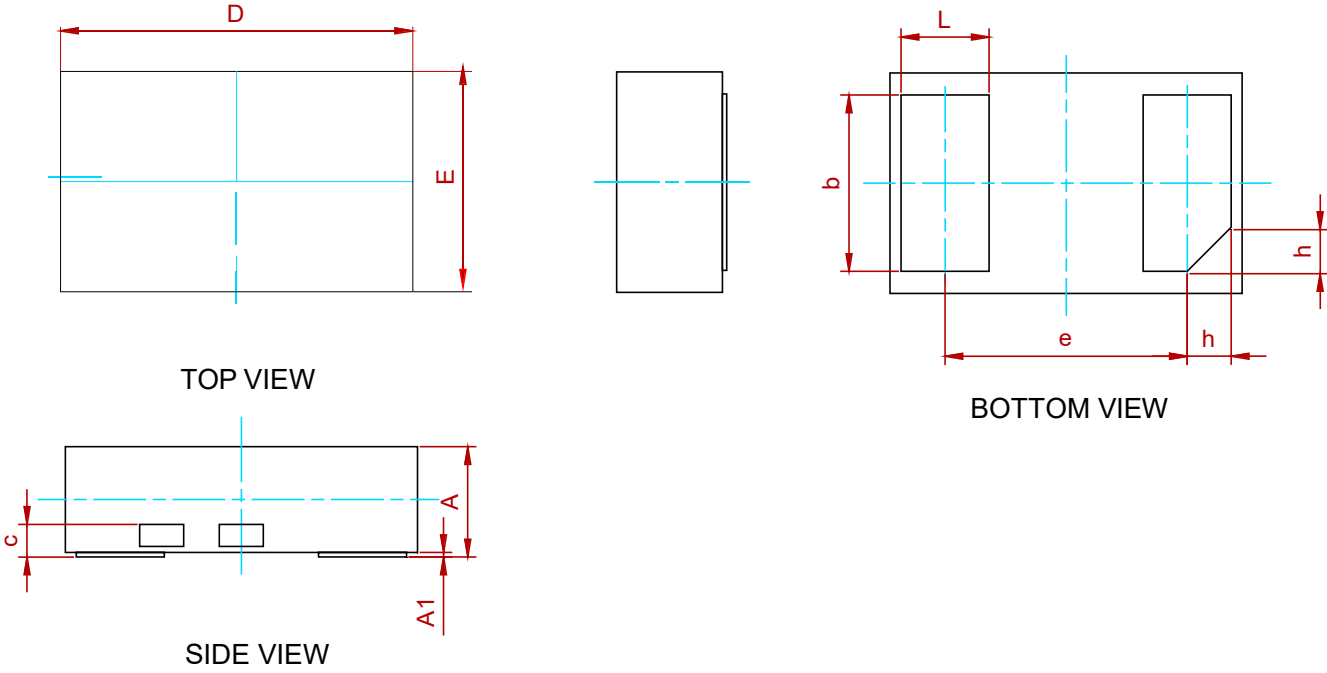


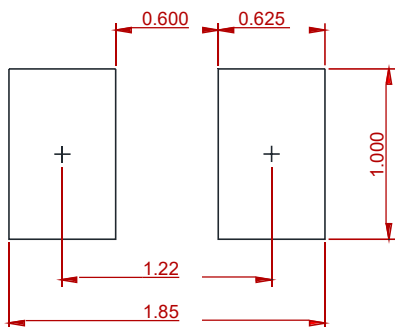
Fig 5. Non Repetitive Peak Pulse Power vs. Pulse time

PACKAGE MECHANICAL DATA



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
c	0.15 Ref.		
b	0.75	0.80	0.85
L	0.35	0.40	0.45
D	1.55	1.60	1.65
E	0.95	1.00	1.05
e	1.10 BSC		
h	0.20 Ref.		

Recommend PCB Layout (Unit: mm)



Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

REEL SPECIFICATION

P/N	PKG	QTY
PTVSHC2EN5VB-MS	DFN1610-2L	3000

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